Product Change Notification: MAAN-10BEUD813

Date:

26-Oct-2026

Product Category:

32-Bit Microcontrollers, PoE PSE

Notification Subject:

CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

Affected CPNs:

MAAN-10BEUD813_Affected_CPN_10262026.pdf
MAAN-10BEUD813_Affected_CPN_10262026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS Free)	QMI519 (PFAS Free)	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	C194	C194	No

Note: The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #**CENO-16EGCZ399**.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 04 March 2026 (date code: 2610)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2025					>	**March 2026**				
Work Week	49	50	51	52	53		10	11	12	13	14
Qual Report Availability			x								
Final PCN Issue Date			x								
Estimated Implementation Date							x				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 15, 2025: Issued final notification.
October 26, 2026: Re-issued final notification to include the test criteria for the Wire Bond Pull (WBP) and Wire Bond Shear (WBS) tests in the Qualification Report. Removed ATSAML11E15A-MFKPH, ATSAML11E16A-MFKPH, ATSAML11E16A-MUKPH, and ATSAML11E16A-MUTKPH catalog part numbers (CPN) from the affected parts list due to their EOL status.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MAAN-10BEUD813_Qual_Report_revA.pdf

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Affected Catalog Part Numbers (CPN):

ATSAMD21G17A-MUTA0

ATSAMD21G18A-MUTN01

ATSAMD21G18A-MUTA1

ATSAMD21G17A-MUTA1

ATSAMD21G18A-MU-SLL

ATSAMD20E16A-MNTA2

ATSAMD20E16A-MU

ATSAMD20E15A-MUA2

ATSAMD20E15A-MU

ATSAMD20E14A-MUA2

ATSAMD20E18A-MN

ATSAMD20E14A-MN

ATSAMD20E17A-MUA2

ATSAMD20E18A-MUTB3

ATSAMD20E18A-MUTB2

ATSAMD20E18A-MUTB1

ATSAMD20E18A-MUTB0

ATSAMD20E17A-MUT

ATSAMD20E18A-MUTA2

ATSAMD20E18A-MUT

ATSAMD20E15A-MUTA2

ATSAMD20E16A-MUTA2

ATSAMD20E17A-MNT

ATSAMD20E15A-MUT

ATSAMD20E14A-MUTA2

ATSAMD20E14A-MUT

ATSAMD20E17A-MN

ATSAMD21G15B-MF

ATSAMD21G16L-MNTP01

ATSAMD21G16L-MNT

ATSAMD21G15B-MFT

ATSAMD21G16B-MUT

ATSAMD21G16B-MFT

ATSAMD21G16L-MUT

ATSAMD21G15B-MUT

ATSAML21E18B-MUT

ATSAML21E18B-MUT-SLL

ATSAML21G18B-MUT-SLL

ATSAML21G18B-MNT

ATSAML21G18B-MUT

ATSAML21G17B-MUT

ATSAML21G16B-MUT

ATSAML21G17B-MNT-SLL

ATSAML21G16B-MNT

ATSAML21G18B-MNT-SLL

ATSAML21G17B-MNT

ATSAML22G17A-MUT

ATSAML22G18A-MUT

ATSAML22G16A-MUT

ATSAMD20E16A-MUA2

ATSAMD20E18A-MUTN02

ATSAMD20E18A-MUTA8

ATSAMD20E18A-MUTN01

ATSAMD20E14B-MNT

ATSAMD20E16B-MNT

ATSAMD20E16B-MUTN01

ATSAMD20E16B-MUT

ATSAMD20G15B-MU

ATSAMD20G15B-MUT

ATSAMD20G16B-MNT

ATSAMD20G15B-MNT

ATSAMD20G15B-MN

ATSAMD20G14B-MN

ATSAMD20G16B-MN

ATSAMD20G16B-MU

ATSAMD20E16A-MNT

ATSAMD20E15A-MNT

ATSAMD20E14A-MNT

ATSAMD20E18A-MUA2

ATSAMD20E16A-MNA2

ATSAMD20E16A-MN

ATSAMD20E15A-MN

ATSAMD20E17A-MU

ATSAMD20E18A-MU

ATSAMD20E17A-MUTA2

ATSAMD20E14A-MU

ATSAMD20E18A-MUTA9

ATSAMD20E18A-MNT

ATSAMD20E16A-MUT

ATSAMC20G18A-MNT

ATSAMC20G17A-MNT

ATSAMC21G16A-MNTS2

ATSAMC21G17A-MUTS2

ATSAMC21G18A-MNT

ATSAMC21G18A-MUTN01

ATSAMC20G18A-MUT

ATSAMC20G17A-MUT

ATSAMC21G18A-MUT

ATSAMC20G15A-MUT

ATSAMD21E15A-MFT

PD69210R-035200-TR

PD69210R-034400

PD69210R-034900

PD69210R-034600

ATSAMD21E17L-MN

ATSAMD21E17D-MU

PD69210C-022419-TR

PD69210C-022419

PD69210R-022420-TR

PD69210R-022420

PD69210R-034400-TR

PD69210R-022320-TR

PD69210R-022320

PD69210C-022319-TR

PD69210R-035200

ATSAMD21E17A-MUT

ATSAMD21E18A-MUTA1

ATSAMD20G14B-MUT

ATSAMD20G14B-MNT

ATSAMD20G14B-MU

ATSAMD20G16B-MUT

ATSAMC21G17A-OMZ

ATSAMC21G18A-MZ-SL3

ATSAMC21G18A-OMZ

ATSAMC21G18A-MZT-SL3

ATSAMC21G15A-MZ

ATSAMC20G18A-MZ

ATSAMC20G17A-MZ

ATSAMC20G16A-MZ

ATSAMC20G18A-MZT

ATSAMC20G17A-MZT

ATSAMC20G16A-MZT

ATSAMC20G15A-MZT

ATSAMC21G18A-MZ

ATSAMC21G16A-MZ

ATSAMC21G17A-MZ

ATSAMC21G18A-MZT

ATSAMC21G17A-MZT

ATSAMC21G16A-MZT

ATSAMC21G15A-MZT

PD39210C-011019-TR

PD39210C-011019

PD39210R-011020

ATSAMD21E17D-MUT

ATSAMD21E17L-MNT

PD69210C-022619-TR

PD69210R-035500

PD69210R-022620-TR

PD69210C-022619

PD69210R-022620

PD77010-0100-0000

ATSAMD21E17L-MF

PD77010-0100-0000-TR

PD77020-011000

PD77020-011000-TR

ATSAMD21G15B-MU

ATSAMD21G16B-MU

ATSAMD21G16B-MF

ATSAMD21E18A-MU

ATSAMD21E18A-MUT

ATSAMD21E17A-MU

ATSAMD21E17A-MUA1

ATSAMD21E18A-MF

ATSAMD21E17A-MFT

ATSAMD21E18A-MFT

ATSAMD21E17A-MUTA1

ATSAMD21E18A-MUA1

ATSAMD21E18A-MU-SLL

ATSAMD21E17A-MF

ATSAMD21E18A-MUTDBG

ATSAMD21E18A-MUDBG

ATSAMD21G18A-MUA1

ATSAMD21G17A-MUT

ATSAMD21G17A-MUA1

ATSAMD21G17A-MU

ATSAMD21G18A-MU

ATSAMD21G18A-MF

ATSAMD21G18A-MFT

ATSAMD21G17A-MFT

ATSAMD21G17A-MF

ATSAMD21G18A-MUT

ATSAMC20G15A-MZ

ATSAMC21E18A-MUTDY

ATSAMC20E17A-MUT

ATSAMC21E18A-MNTDY

ATSAMC20E16A-MUTS2

ATSAMC20E18A-MUT

ATSAMC20E16A-MUT

ATSAMC20E15A-MUT

ATSAMC21E18A-MNT

ATSAMC20E16A-MNT

ATSAMC21E17A-MNT

ATSAMD21E17D-MUT-SLL

PD77020-020400-TR

PD77010-0101-0000

PD77010-0101-0000-TR

ATSAMD21G17D-OMZ

PD77020-020300

PD77020-020300-TR

PD77010-0102-0000-TR

PD77010-0102-0000

PD69210C-022319

ATSAMD20G17A-MUA2

ATSAMD20G15A-MUA2

ATSAMD20G18A-MUA2

ATSAMD20G16A-MUA2

ATSAMD20G18A-MUTA2

ATSAMD20G14A-MUA2

ATSAMD21E16B-MFT

ATSAMD21E15L-MF

ATSAMD21E16L-MNTB7

ATSAMD21E15B-MFTA7

ATSAMD21E16L-MF

ATSAMD21E16B-MU-SLL

ATSAMD21E15B-MF

ATSAMD21E15L-MFT

ATSAMD21E16B-MF

ATSAMD21E16L-MFT

ATSAMD21E15B-MFT

ATSAMD21E15B-MUTN01

ATSAMD21E16L-MNTP01

ATSAMD21E16L-MNT

ATSAMD21E16L-MNTA7

ATSAMD21E16B-MU

ATSAMD21E16B-MUTN02

ATSAMD20G14A-MN

ATSAMD20G18A-MU

ATSAMD20G17A-MU

ATSAMD20G14A-MUTA2

ATSAMD20G17A-MNT

ATSAMD20G16A-MUT

ATSAMD20G15A-MUT

ATSAMD20G16A-MN

ATSAMD20G16A-MU

ATSAMD20G18A-MUT

ATSAMD20G15A-MNT

ATSAMD20G18A-MNT

ATSAMD20G15A-MN

PIC32CM6408MC00048T-I/U5BS2

PIC32CM1216MC00048T-E/U5B

PIC32CM6408MC00048-E/U5B

PIC32CM1216MC00048-I/U5BESU

PIC32CM1216MC00048-I/U5B

PIC32CM1216MC00048T-I/U5BESU

PIC32CM6408MC00048T-I/U5B

PIC32CM1216MC00048T-I/U5B

PIC32CM6408MC00048-I/U5B

PIC32CM6408MC00048T-E/U5B

PIC32CM1216MC00048-E/U5B

ATSAML11E15A-MU

ATSAML10E15A-MU

ATSAML11E16A-MF

ATSAML10E16A-MFT

ATSAML11E14A-MU

ATSAML10E16A-MU

ATSAML10E14A-MU

ATSAML11E15A-MF

ATSAML11E14A-MF

ATSAML10E16A-MF

ATSAML10E15A-MF

ATSAML10E14A-MF

ATSAML11E16A-MFT

ATSAML11E15A-MFT

ATSAML11E14A-MFT

ATSAML10E15A-MFT

ATSAML10E14A-MFT

ATSAML11E16A-MUT

ATSAMD21E16B-MUTN10

ATSAMD21E15B-MU

ATSAMD21E15B-MUT

ATSAMD21E15L-MNT

ATSAMD21E16B-MUT

ATSAMD21G16L-MUTN01

ATSAMD21G16L-MNTA7

ATSAMD20E14B-MN

ATSAMD20E16B-MU

ATSAMD20E14B-MU

ATSAMD20E15B-MU

ATSAMD20E15B-MN

ATSAMD20E16B-MN

ATSAMD20E14B-MUT

ATSAMD20E16B-MUTDY

ATSAMD20E15B-MUTDY

ATSAMD20E15B-MUT

ATSAMD20E15B-MNT

PD77020-020400

ATSAMD21E17L-MFT

PD39210R-011020-TR

PD69210R-035400

PD69210R-035400-TR

PD69210R-035500-TR

ATSAMC21E16A-MNT

ATSAMC21E15A-MNT

ATSAMC20E18A-MNT

ATSAMC20E15A-MNT

ATSAMC21E17A-MUT510

ATSAMC20E17A-MNT

ATSAMC20E17A-MUTS2

ATSAMC21E16A-MNTS2

ATSAMC21E16A-MUTN01

ATSAMC21E18A-MUTN01

ATSAMC21E18A-MUT64

ATSAMC21E18A-MUTS2

ATSAMC21E18A-MUT

ATSAMC21E17A-MUT

ATSAMC21E16A-MUT

ATSAMC21E15A-MUT

ATSAMC21G17A-MZT-SL3

ATSAMC21G17A-MZT-SL2

ATSAMC21G17A-MZT-SL1

ATSAMC20G16A-MNT

ATSAMC21G15A-MUT

ATSAMC20G16A-MUT

ATSAMC20G15A-MNT

ATSAMC21G16A-MUT

ATSAMC21G17A-MU

ATSAMC21G18A-MUT64

ATSAMC20G17A-MUTS2

ATSAMC21G17A-MNT

ATSAMD20G17A-MUTA2

ATSAMD20G16A-MUTA2

ATSAMD20G15A-MUTA2

ATSAMD20G14A-MNT

ATSAMD20G16A-MNT

ATSAMD20G15A-MU

ATSAMD20G17A-MUT

ATSAMD20G14A-MUT

ATSAMD20G14A-MU

ATSAMD20G18A-MN

ATSAMD20G17A-MN

ATSAML11E15A-MUT

ATSAML11E14A-MUT

ATSAML10E16A-MUT

ATSAML10E14A-MUT

ATSAML11E16A-MU

ATSAML10E15A-MUT

ATSAMD21G16B-OMZ

ATSAMD21E16B-MUT-SLL

ATSAMC21G17A-MUT

ATSAMC21G16A-MNT

ATSAMC21G15A-MNT

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MAAN-10BEUD813

Date:
May 7, 2024

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site will qualify by similarity (QBS).

MICROCHIP

Package Qualification Report

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site will qualify by similarity (QBS).

CCB No.: 4601 and 7972

Misc.	Assembly site	MTAI
	BD Number	BDE006697-01
	MP Code (MPC)	66P0145LXYXY
	Part Number (CPN)	PIC32CM5164JH01064-E/5LX
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	T/R - TUBE - TRAY
	Base Quantity Multiple (BQM)	3300 - 40 - 260
	Reliability Site	MPHIL
Lead-Frame	Paddle size	264x264
	Material	C194
	DAP Surface Prep	Cu
	Treatment	BOT on Paddle
	Process	Etched
	Lead-lock	No
	Part Number	10106409
	Lead Plating	Matte Tin
	Strip Size	250x70mm
	Strip Density	120
Bond Wire	Material	CuPdAu
Die Attach	Part Number	3280
	Conductive	Yes
MC	Part Number	G700LTD
PKG	Package Type	VQFN
	Pin/Ball Count	64
	PKG width/size	9 x 9 mm

MICROCHIP

Package Qualification Report

Manufacturing Information

Assembly Lot No.
MTAI242201781.000
MTAI242202179.000
MTAI242202518.000

Result ☑ Pass ☐ Fail ☐ _____

66P01 in VQFN 64 9x9 WF (5LX) package, Standard 125°c using CuPdAu/2N wire, MSL1 assembled in MTAI pass reliability test per QCI-39000 which was conducted at MPHL rel lab. This package is qualified Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test :25°C** M1_SV_1024	JESD22-A113, JIP/ IPC/JEDEC J-STD-020E	231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	Good Devices
	Bake 150°C, 24 hrs System: HERAEUS		231 per lot			
	Moisture Soak 168h(85°C/85%RH) System: VOTSCH VC4034		231 per lot			
	Reflow 3x Convection-Reflow 265°C max System: Mancorp CR.5000F		231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	
	Electrical Test : 25°C M1_SV_1024		231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 500 hrs System: HERAEUS **Electrical Test:** 25°C /130°C System: M1_SV_1024	JESD22-A103	45 units 1 lot	Lot 1 0/45	Pass	
HAST	**Stress Condition:** (Standard) 110°C, 85%RH, 264 hrs. VOLTS=5.5V System: HIRAYAMA HASTEST PC-422R8 **Electrical Test:** 25°C /130ºC System: M1_SV_1024	JESD22-A110	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C
UNBIASED HAST	**Stress Condition:** (Standard) + 110°C, 85%RH, 264 hrs. System: HIRAYAMA HASTEST PC-422R8 **Electrical Test:** 25°C System: M1_SV_1024	JESD22-A118	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	**Stress Condition:** (Standard) - 65°C/150°C, 500 Cycles System : Votsch VTS^{2}7012 **Electrical Test:** 25°C/130ºC System: M1_SV_1024	JESD22-A104	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C
	Wire Bond Pull WBP	Mil. Std. 883-2011	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Wire Bond Pull WBP , 0 Hour	Bond Strength: Wire Pull (>2.5gms)	Mil. Std. 883-2011	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Wire Bond Shear WBS, 0Hour	Bond Strength: Bond Shear (>15 gms)	CDF-AEC-Q100-001	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Standard Pb-free Solderability	>95% lead coverage	J-STD-002E	22 units 1 lot	0/22	Pass	

Product Change Notification: MAAN-10BEUD813

Date:

15-Dec-2025

Product Category:

32-Bit Microcontrollers, PoE PSE

Notification Subject:

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Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)

Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS Free)	QMI519 (PFAS Free)	No
Molding Compound Material	G700LTD	G700LTD	No
Lead-Frame Material	C194	C194	No

Note: The qualification of the new PFAS-free die attach material, QMI519, was officially released via PCN #CENO-16EGCZ399.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 04 March 2026 (date code: 2610)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2025					>	**March 2026**				
Work Week	49	50	51	52	53		10	11	12	13	14
Qual Report Availability			x								
Final PCN Issue Date			x								
Estimated Implementation Date							x				

Method to Identify Change: Traceability Code

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Revision History: December 15, 2025: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

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MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

PD77020-020400

PD77020-020400-TR

PD77010-0101-0000

PD77010-0101-0000-TR

ATSAMD21G17D-OMZ

PD77020-020300

PD77020-020300-TR

PD77010-0102-0000-TR

PD77010-0102-0000

PD69210C-022319

PD69210R-035200-TR

PD69210R-034400

PD69210R-034900

PD69210R-034600

ATSAMD21E17L-MN

ATSAMD21E17D-MU

PD69210C-022419-TR

PD69210C-022419

PD69210R-022420-TR

PD69210R-022420

PD69210R-034400-TR

PD69210R-022320-TR

PD69210R-022320

PD69210C-022319-TR

PD69210R-035200

PD39210C-011019-TR

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

PD39210C-011019

PD39210R-011020

ATSAMD21E17D-MUT

ATSAMD21E17L-MNT

ATSAMD21E17L-MFT

PD39210R-011020-TR

PD69210R-035400

PD69210R-035400-TR

PD69210R-035500-TR

ATSAMD21E17D-MUT-SLL

PD69210C-022619-TR

PD69210R-035500

PD69210R-022620-TR

PD69210C-022619

PD69210R-022620

PD77010-0100-0000

ATSAMD21E17L-MF

PD77010-0100-0000-TR

PD77020-011000

PD77020-011000-TR

ATSAMD21G15B-MU

ATSAMD21G16B-MU

ATSAMD21G16B-MF

ATSAMD21G15B-MF

ATSAMD21G16L-MNTP01

ATSAMD21G16L-MNT

ATSAMD21G15B-MFT

ATSAMD21G16B-MUT

ATSAMD21G16B-MFT

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD21G16L-MUT

ATSAMD21G15B-MUT

ATSAML21E18B-MUT

ATSAML21E18B-MUT-SLL

ATSAML21G18B-MUT-SLL

ATSAML21G18B-MNT

ATSAML21G18B-MUT

ATSAML21G17B-MUT

ATSAML21G16B-MUT

ATSAML21G17B-MNT-SLL

ATSAML21G16B-MNT

ATSAML21G18B-MNT-SLL

ATSAML21G17B-MNT

ATSAML22G17A-MUT

ATSAML22G18A-MUT

ATSAML22G16A-MUT

ATSAMD20E16A-MUA2

ATSAMD20E18A-MUTN02

ATSAMD20E18A-MUTA8

ATSAMD20E18A-MUTN01

ATSAMD20E18A-MUTB3

ATSAMD20E18A-MUTB2

ATSAMD20E18A-MUTB1

ATSAMD20E18A-MUTB0

ATSAMD20E17A-MUT

ATSAMD20E18A-MUTA2

ATSAMD20E18A-MUT

ATSAMD20E15A-MUTA2

ATSAMD20E16A-MUTA2

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD20E17A-MNT

ATSAMD20E15A-MUT

ATSAMD20E14A-MUTA2

ATSAMD20E14A-MUT

ATSAMD20E17A-MN

ATSAMD20E16A-MNT

ATSAMD20E15A-MNT

ATSAMD20E14A-MNT

ATSAMD20E18A-MUA2

ATSAMD20E16A-MNA2

ATSAMD20E16A-MN

ATSAMD20E15A-MN

ATSAMD20E17A-MU

ATSAMD20E18A-MU

ATSAMD20E17A-MUTA2

ATSAMD20E14A-MU

ATSAMD20E18A-MUTA9

ATSAMD20E18A-MNT

ATSAMD20E16A-MUT

ATSAMD20G17A-MUA2

ATSAMD20G15A-MUA2

ATSAMD20G18A-MUA2

ATSAMD20G16A-MUA2

ATSAMD20G18A-MUTA2

ATSAMD20G14A-MUA2

ATSAMD20G17A-MUTA2

ATSAMD20G16A-MUTA2

ATSAMD20G15A-MUTA2

ATSAMD20G14A-MNT

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD20G16A-MNT

ATSAMD20G15A-MU

ATSAMD20G17A-MUT

ATSAMD20G14A-MUT

ATSAMD20G14A-MU

ATSAMD20G18A-MN

ATSAMD20G17A-MN

ATSAML11E15A-MUT

ATSAML11E14A-MUT

ATSAML10E16A-MUT

ATSAML10E14A-MUT

ATSAML11E16A-MU

ATSAML10E15A-MUT

ATSAMD21G16B-OMZ

ATSAMD21E16B-MUT-SLL

ATSAMD21E16B-MFT

ATSAMD21E15L-MF

ATSAMD21E16L-MNTB7

ATSAMD21E15B-MFTA7

ATSAMD21E16L-MF

ATSAMD21E16B-MU-SLL

ATSAMD21E15B-MF

ATSAMD21E15L-MFT

ATSAMD21E16B-MF

ATSAMD21E16L-MFT

ATSAMD21E15B-MFT

ATSAMD21E15B-MUTN01

ATSAMD21E16L-MNTP01

ATSAMD21E16L-MNT

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD21E16L-MNTA7

ATSAMD21E16B-MU

ATSAMD21E16B-MUTN02

ATSAMD20G14A-MN

ATSAMD20G18A-MU

ATSAMD20G17A-MU

ATSAMD20G14A-MUTA2

ATSAMD20G17A-MNT

ATSAMD20G16A-MUT

ATSAMD20G15A-MUT

ATSAMD20G16A-MN

ATSAMD20G16A-MU

ATSAMD20G18A-MUT

ATSAMD20G15A-MNT

ATSAMD20G18A-MNT

ATSAMD20G15A-MN

PIC32CM6408MC00048T-I/U5BS2

PIC32CM1216MC00048T-E/U5B

PIC32CM6408MC00048-E/U5B

PIC32CM1216MC00048-I/U5BESU

PIC32CM1216MC00048-I/U5B

PIC32CM1216MC00048T-I/U5BESU

PIC32CM6408MC00048T-I/U5B

PIC32CM1216MC00048T-I/U5B

PIC32CM6408MC00048-I/U5B

PIC32CM6408MC00048T-E/U5B

PIC32CM1216MC00048-E/U5B

ATSAML11E15A-MFKPH

ATSAML11E16A-MFKPH

Date: Sunday, December 14, 2025

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAML11E16A-MUKPH

ATSAML11E16A-MUTKPH

ATSAML11E15A-MU

ATSAML10E15A-MU

ATSAML11E16A-MF

ATSAML10E16A-MFT

ATSAML11E14A-MU

ATSAML10E16A-MU

ATSAML10E14A-MU

ATSAML11E15A-MF

ATSAML11E14A-MF

ATSAML10E16A-MF

ATSAML10E15A-MF

ATSAML10E14A-MF

ATSAML11E16A-MFT

ATSAML11E15A-MFT

ATSAML11E14A-MFT

ATSAML10E15A-MFT

ATSAML10E14A-MFT

ATSAML11E16A-MUT

ATSAMD21E16B-MUTN10

ATSAMD21E15B-MU

ATSAMD21E15B-MUT

ATSAMD21E15L-MNT

ATSAMD21E16B-MUT

ATSAMD21G16L-MUTN01

ATSAMD21G16L-MNTA7

ATSAMD20E14B-MN

ATSAMD20E16B-MU

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD20E14B-MU

ATSAMD20E15B-MU

ATSAMD20E15B-MN

ATSAMD20E16B-MN

ATSAMD20E14B-MUT

ATSAMD20E16B-MUTDY

ATSAMD20E15B-MUTDY

ATSAMD20E15B-MUT

ATSAMD20E15B-MNT

ATSAMD20E14B-MNT

ATSAMD20E16B-MNT

ATSAMD20E16B-MUTN01

ATSAMD20E16B-MUT

ATSAMD20G15B-MU

ATSAMD20G15B-MUT

ATSAMD20G16B-MNT

ATSAMD20G15B-MNT

ATSAMD20G15B-MN

ATSAMD20G14B-MN

ATSAMD20G16B-MN

ATSAMD20G16B-MU

ATSAMD20G14B-MUT

ATSAMD20G14B-MNT

ATSAMD20G14B-MU

ATSAMD20G16B-MUT

ATSAMC21G17A-OMZ

ATSAMC21G18A-MZ-SL3

ATSAMC21G18A-OMZ

ATSAMC21G18A-MZT-SL3

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMC21G15A-MZ

ATSAMC20G18A-MZ

ATSAMC20G17A-MZ

ATSAMC20G16A-MZ

ATSAMC20G18A-MZT

ATSAMC20G17A-MZT

ATSAMC20G16A-MZT

ATSAMC20G15A-MZT

ATSAMC21G18A-MZ

ATSAMC21G16A-MZ

ATSAMC21G17A-MZ

ATSAMC21G18A-MZT

ATSAMC21G17A-MZT

ATSAMC21G16A-MZT

ATSAMC21G15A-MZT

ATSAMC20G15A-MZ

ATSAMC21E18A-MUTDY

ATSAMC20E17A-MUT

ATSAMC21E18A-MNTDY

ATSAMC20E16A-MUTS2

ATSAMC20E18A-MUT

ATSAMC20E16A-MUT

ATSAMC20E15A-MUT

ATSAMC21E18A-MNT

ATSAMC20E16A-MNT

ATSAMC21E17A-MNT

ATSAMC21E16A-MNT

ATSAMC21E15A-MNT

ATSAMC20E18A-MNT

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMC20E15A-MNT

ATSAMC21E17A-MUT510

ATSAMC20E17A-MNT

ATSAMC20E17A-MUTS2

ATSAMC21E16A-MNTS2

ATSAMC21E16A-MUTN01

ATSAMC21E18A-MUTN01

ATSAMC21E18A-MUT64

ATSAMC21E18A-MUTS2

ATSAMC21E18A-MUT

ATSAMC21E17A-MUT

ATSAMC21E16A-MUT

ATSAMC21E15A-MUT

ATSAMC21G17A-MZT-SL3

ATSAMC21G17A-MZT-SL2

ATSAMC21G17A-MZT-SL1

ATSAMC20G16A-MNT

ATSAMC21G15A-MUT

ATSAMC20G16A-MUT

ATSAMC20G15A-MNT

ATSAMC21G16A-MUT

ATSAMC21G17A-MU

ATSAMC21G18A-MUT64

ATSAMC20G17A-MUTS2

ATSAMC21G17A-MNT

ATSAMC21G17A-MUT

ATSAMC21G16A-MNT

ATSAMC21G15A-MNT

ATSAMC20G18A-MNT

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMC20G17A-MNT

ATSAMC21G16A-MNTS2

ATSAMC21G17A-MUTS2

ATSAMC21G18A-MNT

ATSAMC21G18A-MUTN01

ATSAMC20G18A-MUT

ATSAMC20G17A-MUT

ATSAMC21G18A-MUT

ATSAMC20G15A-MUT

ATSAMD21E15A-MFT

ATSAMD21E17A-MUT

ATSAMD21E18A-MUTA1

ATSAMD21E18A-MU

ATSAMD21E18A-MUT

ATSAMD21E17A-MU

ATSAMD21E17A-MUA1

ATSAMD21E18A-MF

ATSAMD21E17A-MFT

ATSAMD21E18A-MFT

ATSAMD21E17A-MUTA1

ATSAMD21E18A-MUA1

ATSAMD21E18A-MU-SLL

ATSAMD21E17A-MF

ATSAMD21E18A-MUTDBG

ATSAMD21E18A-MUDBG

ATSAMD21G18A-MUA1

ATSAMD21G17A-MUT

ATSAMD21G17A-MUA1

ATSAMD21G17A-MU

Date: Sunday, December 14, 2025

MAAN-10BEUD813 - CCB 7972 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site.

ATSAMD21G18A-MU

ATSAMD21G18A-MF

ATSAMD21G18A-MFT

ATSAMD21G17A-MFT

ATSAMD21G17A-MF

ATSAMD21G18A-MUT

ATSAMD21G17A-MUTA0

ATSAMD21G18A-MUTN01

ATSAMD21G18A-MUTA1

ATSAMD21G17A-MUTA1

ATSAMD21G18A-MU-SLL

ATSAMD20E16A-MNTA2

ATSAMD20E16A-MU

ATSAMD20E15A-MUA2

ATSAMD20E15A-MU

ATSAMD20E14A-MUA2

ATSAMD20E18A-MN

ATSAMD20E14A-MN

ATSAMD20E17A-MUA2

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: MAAN-10BEUD813

Date:
May 7, 2024

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site will qualify by similarity (QBS).

MICROCHIP

Package Qualification Report

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire for selected ATSAMC20E1, ATSAMC20G1, ATSAMC21E1, ATSAMC21G1, ATSAMD20E1, ATSAMD20G1, ATSAMD21E1, ATSAMD21G1, ATSAML10E1, ATSAML11E1, ATSAML21E1, ATSAML21G1, ATSAML22G1, PD39210, PD69210, PD77010, PD77020, PIC32CM1216MC00048, and PIC32CM6408MC00048 device families available various packages at MTAI assembly site will qualify by similarity (QBS).

CCB No.: 4601 and 7972

Misc.	Assembly site	MTAI
	BD Number	BDE006697-01
	MP Code (MPC)	66P0145LXYXY
	Part Number (CPN)	PIC32CM5164JH01064-E/5LX
	MSL information	MSL1
	Assembly Shipping Media (T/R, Tube/Tray)	T/R - TUBE - TRAY
	Base Quantity Multiple (BQM)	3300 - 40 - 260
	Reliability Site	MPHIL
Lead-Frame	Paddle size	264x264
	Material	C194
	DAP Surface Prep	Cu
	Treatment	BOT on Paddle
	Process	Etched
	Lead-lock	No
	Part Number	10106409
	Lead Plating	Matte Tin
	Strip Size	250x70mm
	Strip Density	120
Bond Wire	Material	CuPdAu
Die Attach	Part Number	3280
	Conductive	Yes
MC	Part Number	G700LTD
PKG	Package Type	VQFN
	Pin/Ball Count	64
	PKG width/size	9 x 9 mm

MICROCHIP

Package Qualification Report

Manufacturing Information

Assembly Lot No.
MTAI242201781.000
MTAI242202179.000
MTAI242202518.000

Result ☑ Pass ☐ Fail ☐ _____

66P01 in VQFN 64 9x9 WF (5LX) package, Standard 125°c using CuPdAu/2N wire, MSL1 assembled in MTAI pass reliability test per QCI-39000 which was conducted at MPHL rel lab. This package is qualified Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test :25°C** M1_SV_1024	JESD22-A113, JIP/ IPC/JEDEC J-STD-020E	231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	Good Devices
	Bake 150°C, 24 hrs System: HERAEUS		231 per lot			
	Moisture Soak 168h(85°C/85%RH) System: VOTSCH VC4034		231 per lot			
	Reflow 3x Convection-Reflow 265°C max System: Mancorp CR.5000F		231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	
	Electrical Test : 25°C M1_SV_1024		231 per lot	Lot 1 0/231 Lot 2 0/231 Lot 3 0/231	Pass Pass Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 500 hrs System: HERAEUS **Electrical Test:** 25°C /130°C System: M1_SV_1024	JESD22-A103	45 units 1 lot	Lot 1 0/45	Pass	
HAST	**Stress Condition:** (Standard) 110°C, 85%RH, 264 hrs. VOLTS=5.5V System: HIRAYAMA HASTEST PC-422R8 **Electrical Test:** 25°C /130ºC System: M1_SV_1024	JESD22-A110	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C
UNBIASED HAST	**Stress Condition:** (Standard) + 110°C, 85%RH, 264 hrs. System: HIRAYAMA HASTEST PC-422R8 **Electrical Test:** 25°C System: M1_SV_1024	JESD22-A118	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	**Stress Condition:** (Standard) - 65°C/150°C, 500 Cycles System : Votsch VTS²7012 **Electrical Test:** 25°C/130ºC System: M1_SV_1024	JESD22-A104	77 units per lot	Lot 1 0/77 Lot 2 0/77 Lot 3 0/77	Pass Pass Pass	Parts had been pre-conditioned at 260°C
	Wire Bond Pull WBP	Mil. Std. 883-2011	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Wire Bond Pull WBP , 0 Hour		Mil. Std. 883-2011	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Wire Bond Shear WBS, 0Hour		CDF-AEC-Q100-001	5 units, 30 bonds 1 lot	Lot 1 0/30	Pass	
Standard Pb-free Solderability	>95% lead coverage	J-STD-002E	22 units 1 lot	0/22	Pass	